

ABSTRACT

Provided are a device and method for bonding alignment. The device for bonding alignment comprises a press assembly and an objective lens group (105) located at one side of the press assembly. The press assembly comprises a first chuck (103) and a rotatable second chuck (104). If surfaces of the first and second chucks are not parallel to each other, the second chuck is rotated such that the surfaces of the first and second chucks are parallel to each other. Next, a first substrate (301) is loaded to the first chuck. Since one side of the press assembly is provided with the objective lens group, an alignment mark (302) on the first substrate can be observed. Next, a second substrate (501) is loaded to the second chuck. The objective lens group is used to observe an alignment mark (502) on the second substrate. The two substrates are moved according to an observation result obtained by means of the objective lens group, such that the alignment marks of the two substrates are aligned, thereby realizing bonding alignment of the two substrates. The method for bonding alignment comprises, chucks are adjusted first, and then substrates are aligned. The invention does not need a very high precision device, thereby reducing complexity of a device. Moreover, adjusting chucks first ensures global precision control with respect to alignment of substrates, and can in particular reduce wedge error resulting from bonding of deformed substrates.